

MN34120PA Data Sheet

■ Overview

This product is MOS type image sensor of Type-1/2.33" 16.37 mega pixels. R,G,B primary color mosaic filters are used as the color filters. In the still mode, the signal of 16.37 mega pixels can be output to the high-resolution ultra-high-density. The FHD movie is achieved by vertical and horizontal mixing.

■ Feature

Parameter	Content	
Scan mode	Progressive scan	
Optical size	1/2.33 type 4:3 aspect	
Number of effective pixels	4,660 (H) × 3,512 (V) = 16,365,920 (pixel)	
Number of active pixels	4,632 (H) × 3,488 (V) = 16,156,416 (pixel)	
Total number of pixels	4,804 (H) × 3,648 (V) = 17,524,992 (pixel)	
Pixel size	1.335 (H) μm × 1.335 (V) μm	
Package	LGA Package (Ceramics)	
Actual imaging area dimensions (active pixel area)	6183.72 (H) μm × 4656.48 (V) μm	
Color filter arrangement	R,G,B primary color mosaic filters	
Power supply voltage	3.3V / 1.8V / 1.2V	
Master clock	Typ. 54 MHz	
Output signal type	subLVDS DDR method 648 Mbps	
Register I/F	4-wire Serial I/F	
Driving mode	Full scan1(1ch8port/12bit) Full scan2(1ch8port/10bit) 1080p mode(1ch6port/12bit) 720p mode(1ch4port/12bit) Monitor mode(1ch2port/12bit)	16fps : 4632H × 3488V 22fps : 4632H × 3488V 60fps : 2314H × 1304V 60fps : 1543H × 872V 30fps : 1543H × 496V

■ Application

Digital Still Camera
Camcorder

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